

NCV8440

Protected Power MOSFET

2.6 A, 52 V, N-Channel, Logic Level,
Clamped MOSFET w/ ESD Protection

Benefits

- High Energy Capability for Inductive Loads
- Low Switching Noise Generation

Features

- Diode Clamp Between Gate and Source
- ESD Protection – HBM 5000 V
- Active Over-Voltage Gate to Drain Clamp
- Scalable to Lower or Higher $R_{DS(on)}$
- Internal Series Gate Resistance
- These are Pb-Free Devices

Applications

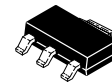
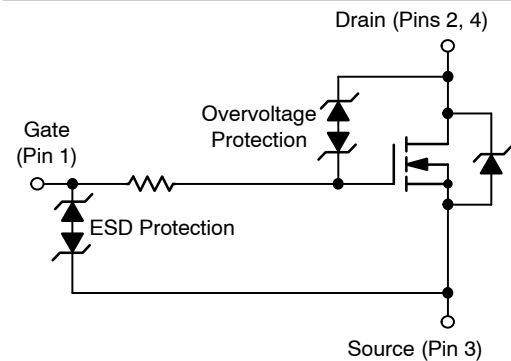
- Automotive and Industrial Markets:
Solenoid Drivers, Lamp Drivers, Small Motor Drivers
- NCV Prefix for Automotive and Other Applications Requiring Site and Control Changes



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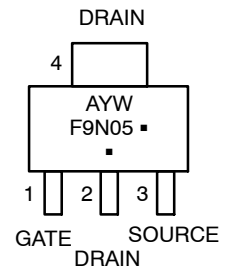
| V_{DSS} (Clamped) | $R_{DS(on)}$ TYP | I_D MAX |
|------------------------|------------------|-----------|
| 52 V | 95 mΩ @ 10 V | 2.6 A |



SOT-223
CASE 318E
STYLE 3

- 1 = Gate
- 2 = Drain
- 3 = Source

MARKING DIAGRAM



- A = Assembly Location
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

| Device | Package | Shipping† |
|--------------|----------------------|------------------|
| NCV8440STT1G | SOT-223 (Pb-Free) | 1000/Tape & Reel |
| NCV8440STT3G | SOT-223 (Pb-Free) | 4000/Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

NCV8440

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

| Rating | Symbol | Value | Unit |
|--|-----------------|------------|--------------------|
| Drain-to-Source Voltage Internally Clamped | V_{DSS} | 52-59 | V |
| Gate-to-Source Voltage - Continuous | V_{GS} | ± 15 | V |
| Drain Current - Continuous @ $T_A = 25^\circ\text{C}$ - Single Pulse ($t_p = 10 \mu\text{s}$) (Note 1) | I_D | 2.6 | A |
| | I_{DM} | 10 | A |
| Total Power Dissipation @ $T_A = 25^\circ\text{C}$ (Note 1) | P_D | 1.69 | W |
| Operating and Storage Temperature Range | T_J, T_{stg} | -55 to 150 | $^\circ\text{C}$ |
| Single Pulse Drain-to-Source Avalanche Energy ($V_{DD} = 50 \text{ V}$, $I_{D(pk)} = 1.17 \text{ A}$, $V_{GS} = 10 \text{ V}$, $L = 160 \text{ mH}$, $R_G = 25 \Omega$) | E_{AS} | 110 | mJ |
| Load Dump Voltage ($V_{GS} = 0$ and 10 V , $R_I = 2.0 \Omega$, $R_L = 9.0 \Omega$, $t_d = 400 \text{ ms}$) | V_{LD} | 60 | V |
| Thermal Resistance, Junction-to-Ambient (Note 1) Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 74 | $^\circ\text{C/W}$ |
| | $R_{\theta JA}$ | 169 | $^\circ\text{C/W}$ |
| Maximum Lead Temperature for Soldering Purposes, 1/8" from Case for 10 Seconds | T_L | 260 | $^\circ\text{C}$ |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- When surface mounted to a FR4 board using 1" pad size, (Cu area 1.127 in²).
- When surface mounted to a FR4 board using minimum recommended pad size, (Cu area 0.412 in²).

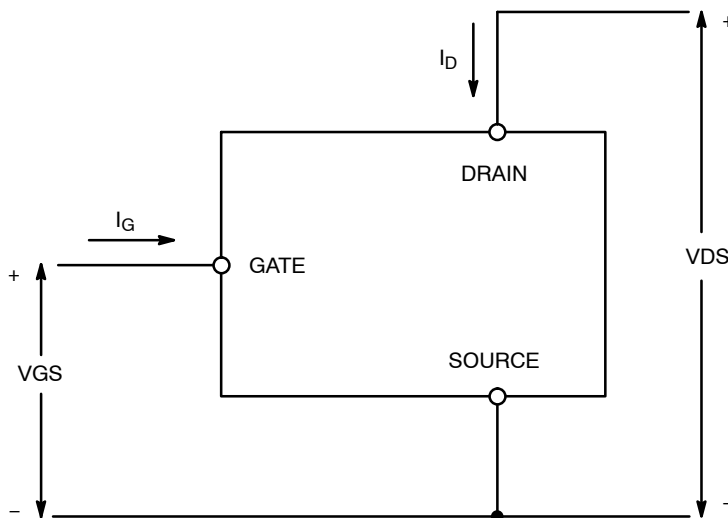


Figure 1. Voltage and Current Convention

NCV8440

MOSFET ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|----------------|--------|-----|-----|-----|------|
|----------------|--------|-----|-----|-----|------|

OFF CHARACTERISTICS

| | | | | | |
|---|---------------|------------|------------------|------------|--------------------------------|
| Drain-to-Source Breakdown Voltage (Note 3) ($V_{GS} = 0\text{ V}$, $I_D = 1.0\text{ mA}$, $T_J = 25^\circ\text{C}$) ($V_{GS} = 0\text{ V}$, $I_D = 1.0\text{ mA}$, $T_J = -40^\circ\text{C}$ to 125°C) (Note 4) Temperature Coefficient (Negative) | $V_{(BR)DSS}$ | 52 50.8 | 55 54 -9.3 | 59 59.5 | V V mV/ $^\circ\text{C}$ |
| Zero Gate Voltage Drain Current ($V_{DS} = 40\text{ V}$, $V_{GS} = 0\text{ V}$) ($V_{DS} = 40\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 125^\circ\text{C}$) (Note 4) | I_{DSS} | | | 10 25 | μA |
| Gate-Body Leakage Current ($V_{GS} = \pm 8\text{ V}$, $V_{DS} = 0\text{ V}$) ($V_{GS} = \pm 14\text{ V}$, $V_{DS} = 0\text{ V}$) | I_{GSS} | | ± 35 | ± 10 | μA |

ON CHARACTERISTICS (Note 3)

| | | | | | |
|--|--------------|-----|------------------|-------------------|---------------------------|
| Gate Threshold Voltage (Note 3) ($V_{DS} = V_{GS}$, $I_D = 100\text{ }\mu\text{A}$) Threshold Temperature Coefficient (Negative) | $V_{GS(th)}$ | 1.1 | 1.5 -4.1 | 1.9 | V mV/ $^\circ\text{C}$ |
| Static Drain-to-Source On-Resistance (Note 3) ($V_{GS} = 3.5\text{ V}$, $I_D = 0.6\text{ A}$) ($V_{GS} = 4.0\text{ V}$, $I_D = 1.5\text{ A}$) ($V_{GS} = 10\text{ V}$, $I_D = 2.6\text{ A}$) | $R_{DS(on)}$ | | 135 150 95 | 180 160 110 | m Ω |
| Forward Transconductance (Note 3) ($V_{DS} = 15\text{ V}$, $I_D = 2.6\text{ A}$) | g_{FS} | | 3.8 | | Mhos |

DYNAMIC CHARACTERISTICS

| | | | | | | |
|----------------------|---|-----------|--|-----|--|---------------|
| Input Capacitance | $V_{DS} = 35\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 10\text{ kHz}$ | C_{iss} | | 155 | | μF |
| Output Capacitance | | C_{oss} | | 60 | | |
| Transfer Capacitance | | C_{rss} | | 25 | | |
| Input Capacitance | $V_{DS} = 25\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 10\text{ kHz}$ | C_{iss} | | 170 | | μF |
| Output Capacitance | | C_{oss} | | 70 | | |
| Transfer Capacitance | | C_{rss} | | 30 | | |

- Pulse Test: Pulse Width $\leq 300\text{ }\mu\text{s}$, Duty Cycle $\leq 2\%$.
- Not subject to production testing.
- Switching characteristics are independent of operating junction temperatures.

NCV8440

MOSFET ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

| Characteristic | | Symbol | Min | Typ | Max | Unit |
|---|--|--------------|-----|------|-----|------|
| SWITCHING CHARACTERISTICS (Note 5) | | | | | | |
| Turn-On Delay Time | $V_{GS} = 4.5\text{ V}, V_{DD} = 40\text{ V},$ $I_D = 2.6\text{ A}, R_D = 15.4\ \Omega$ | $t_{d(on)}$ | | 375 | | ns |
| Rise Time | | t_r | | 1525 | | |
| Turn-Off Delay Time | | $t_{d(off)}$ | | 1530 | | |
| Fall Time | | t_f | | 1160 | | |
| Turn-On Delay Time | $V_{GS} = 4.5\text{ V}, V_{DD} = 40\text{ V},$ $I_D = 1.0\text{ A}, R_D = 40\ \Omega$ | $t_{d(on)}$ | | 325 | | ns |
| Rise Time | | t_r | | 1275 | | |
| Turn-Off Delay Time | | $t_{d(off)}$ | | 1860 | | |
| Fall Time | | t_f | | 1150 | | |
| Turn-On Delay Time | $V_{GS} = 10\text{ V}, V_{DD} = 15\text{ V},$ $I_D = 2.6\text{ A}, R_D = 5.8\ \Omega$ | $t_{d(on)}$ | | 190 | | ns |
| Rise Time | | t_r | | 710 | | |
| Turn-Off Delay Time | | $t_{d(off)}$ | | 2220 | | |
| Fall Time | | t_f | | 1180 | | |
| Gate Charge | $V_{GS} = 4.5\text{ V}, V_{DS} = 40\text{ V},$ $I_D = 2.6\text{ A (Note 3)}$ | Q_T | | 4.5 | | nC |
| | | Q_1 | | 0.9 | | |
| | | Q_2 | | 2.6 | | |
| Gate Charge | $V_{GS} = 4.5\text{ V}, V_{DS} = 15\text{ V},$ $I_D = 1.5\text{ A (Note 3)}$ | Q_T | | 3.9 | | nC |
| | | Q_1 | | 1.0 | | |
| | | Q_2 | | 1.7 | | |

SOURCE-DRAIN DIODE CHARACTERISTICS

| | | | | | | |
|--------------------------------|--|----------|--|--------------|-----|---------------|
| Forward On-Voltage | $I_S = 2.6\text{ A}, V_{GS} = 0\text{ V (Note 3)}$ $I_S = 2.6\text{ A}, V_{GS} = 0\text{ V}, T_J = 125^\circ\text{C}$ | V_{SD} | | 0.81 0.66 | 1.5 | V |
| Reverse Recovery Time | $I_S = 1.5\text{ A}, V_{GS} = 0\text{ V},$ $di_S/dt = 100\text{ A}/\mu\text{s (Note 3)}$ | t_{rr} | | 730 | | ns |
| | | t_a | | 200 | | |
| | | t_b | | 530 | | |
| Reverse Recovery Stored Charge | | Q_{RR} | | 6.3 | | μC |

ESD CHARACTERISTICS (Note 4)

| | | | | | | |
|-------------------------------------|------------------------|-----|------|--|--|---|
| Electro-Static Discharge Capability | Human Body Model (HBM) | ESD | 5000 | | | V |
| | Machine Model (MM) | | 500 | | | |

- Pulse Test: Pulse Width $\leq 300\ \mu\text{s}$, Duty Cycle $\leq 2\%$.
- Not subject to production testing.
- Switching characteristics are independent of operating junction temperatures.

TYPICAL PERFORMANCE CURVES

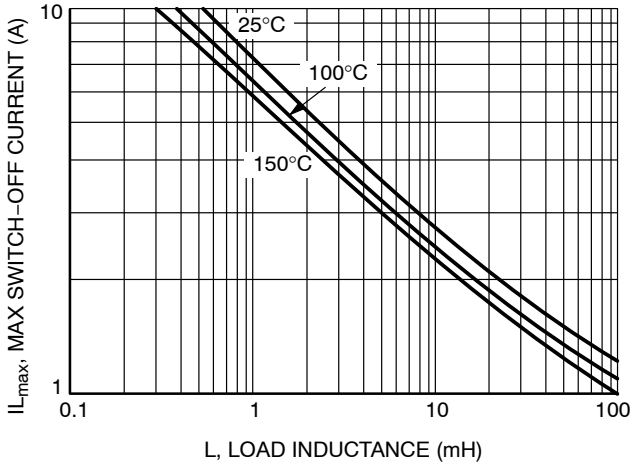


Figure 1. Single Pulse Maximum Switch-off Current vs. Load Inductance

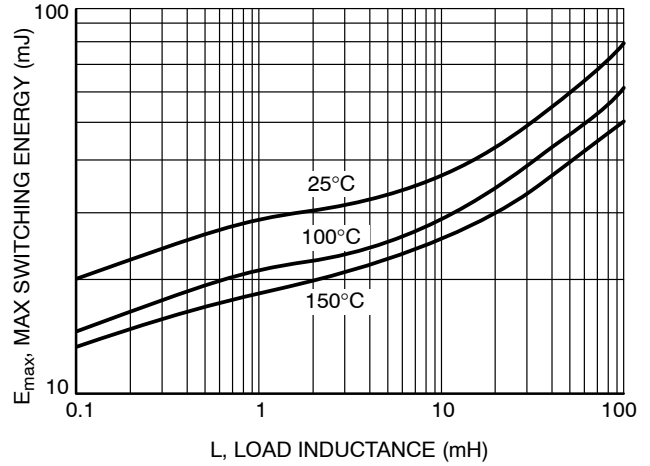


Figure 2. Single Pulse Maximum Switching Energy vs. Load Inductance

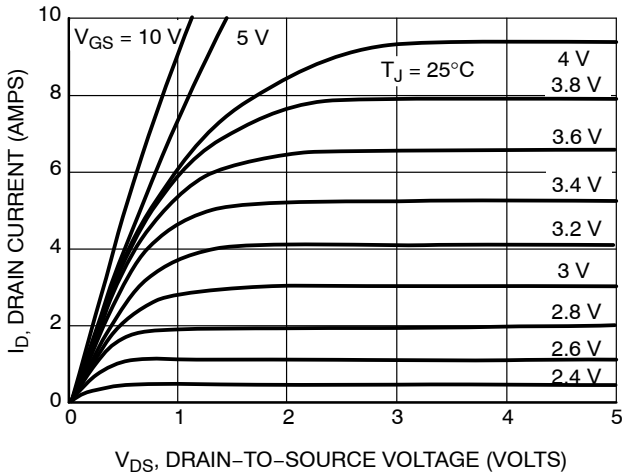


Figure 3. On-State Output Characteristics

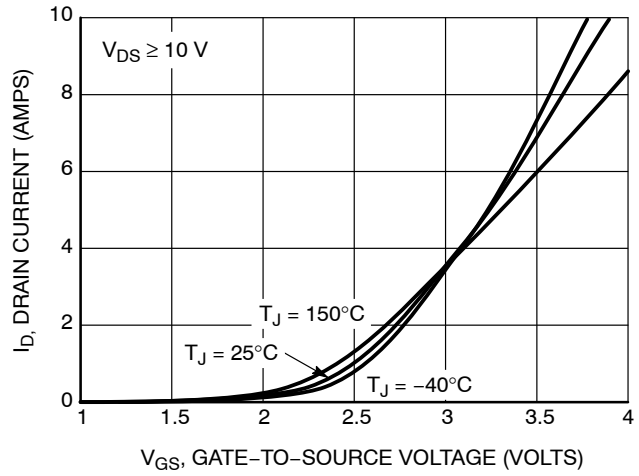


Figure 4. Transfer Characteristics

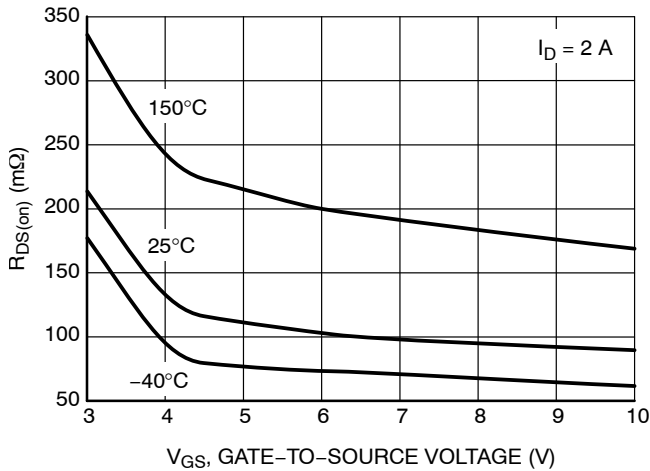


Figure 5. $R_{DS(on)}$ vs. Gate-Source Voltage

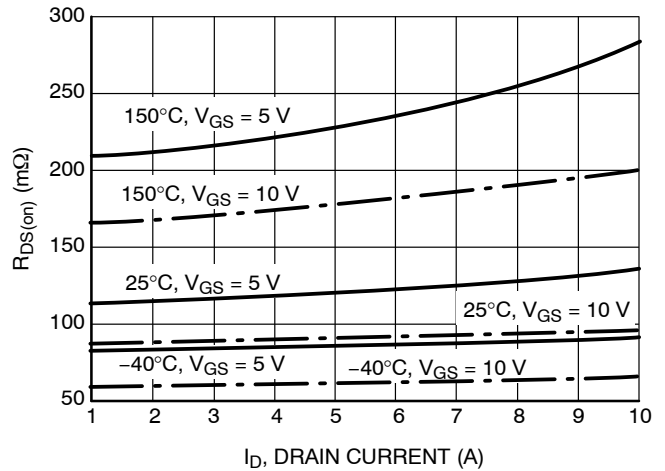


Figure 6. $R_{DS(on)}$ vs. Drain Current

TYPICAL PERFORMANCE CURVES

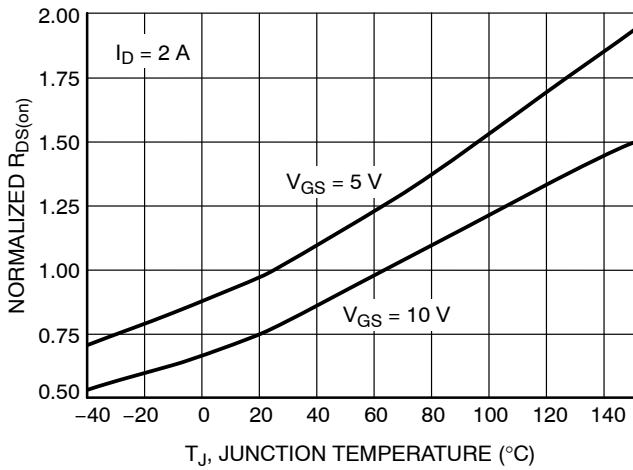


Figure 7. Normalized $R_{DS(on)}$ vs. Temperature

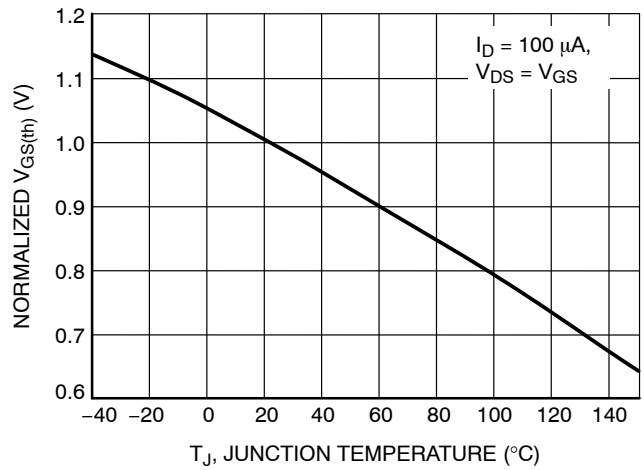


Figure 8. Normalized Threshold Voltage vs. Temperature

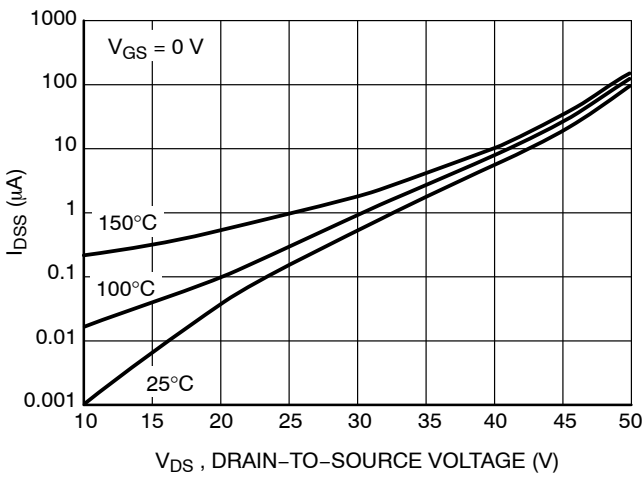


Figure 9. Drain-to-Source Leakage Current

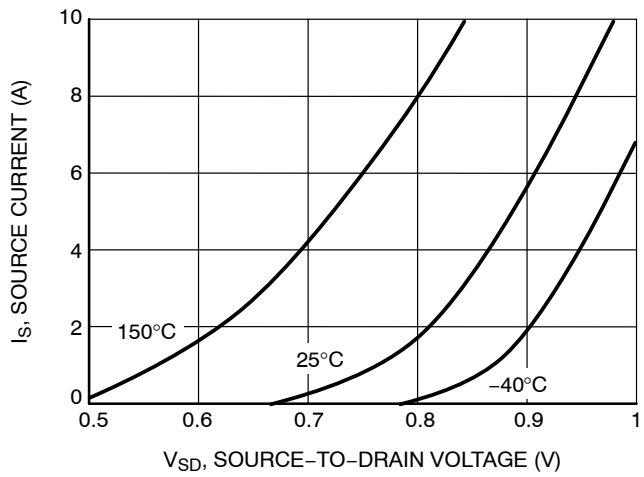


Figure 10. Source-Drain Diode Forward Characteristics

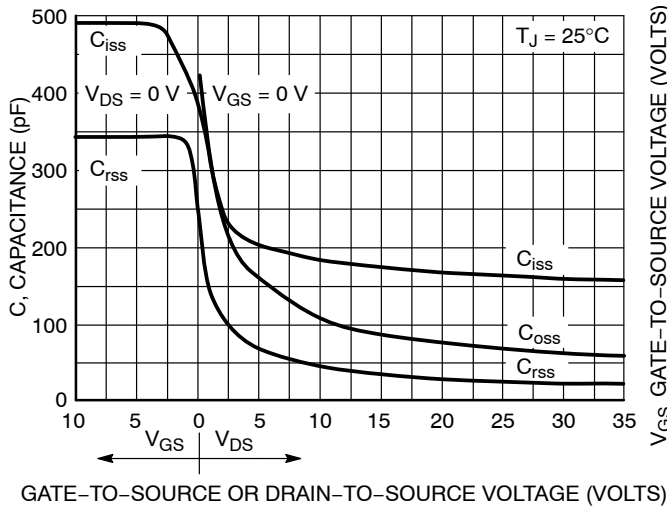


Figure 11. Capacitance Variation

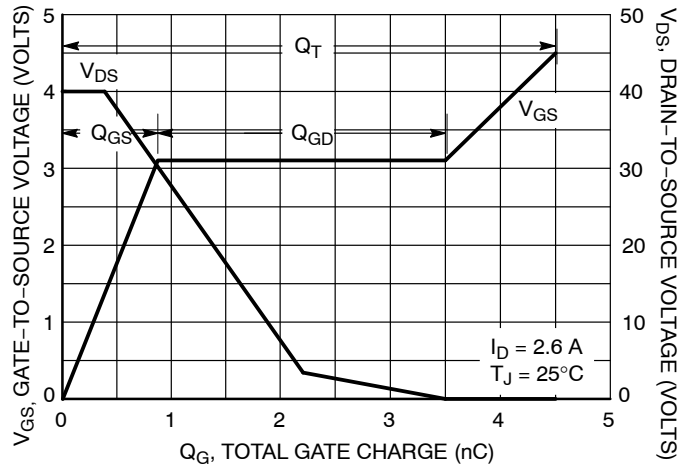


Figure 12. Gate-to-Source Voltage vs. Total Gate Charge

TYPICAL PERFORMANCE CURVES

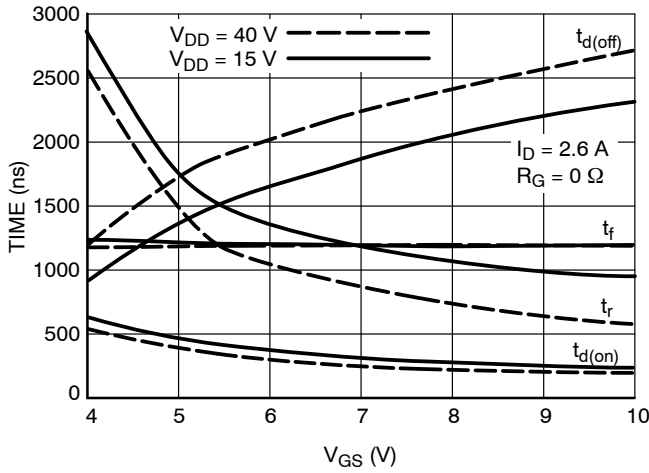


Figure 13. Resistive Load Switching Time vs. Gate-Source Voltage

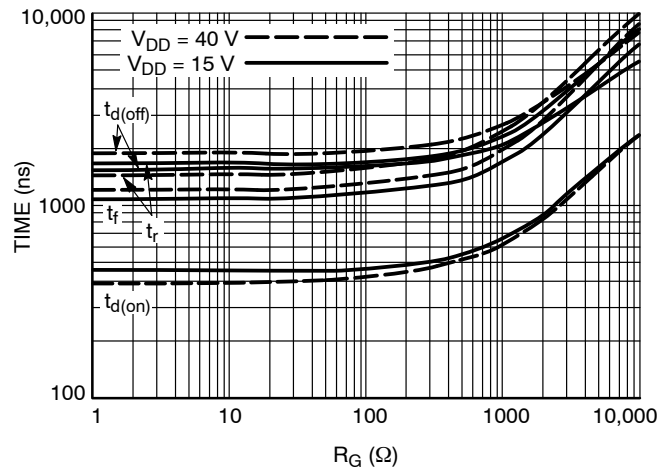


Figure 14. Resistive Load Switching Time vs. Gate Resistance ($V_{GS} = 5\text{ V}$, $I_D = 2.6\text{ A}$)

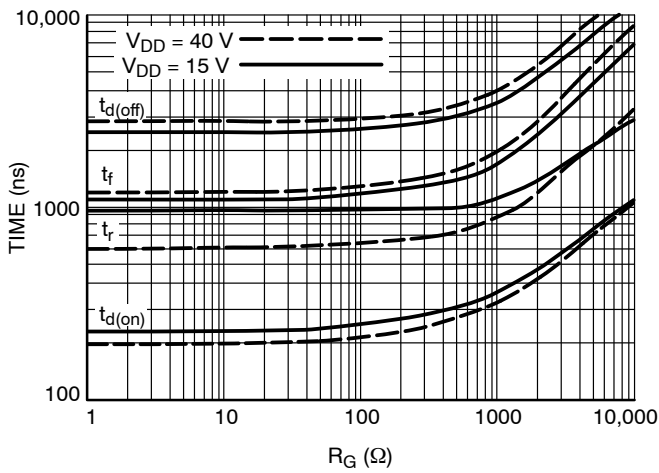


Figure 15. Resistive Load Switching Time vs. Gate Resistance ($V_{GS} = 10\text{ V}$, $I_D = 2.6\text{ A}$)

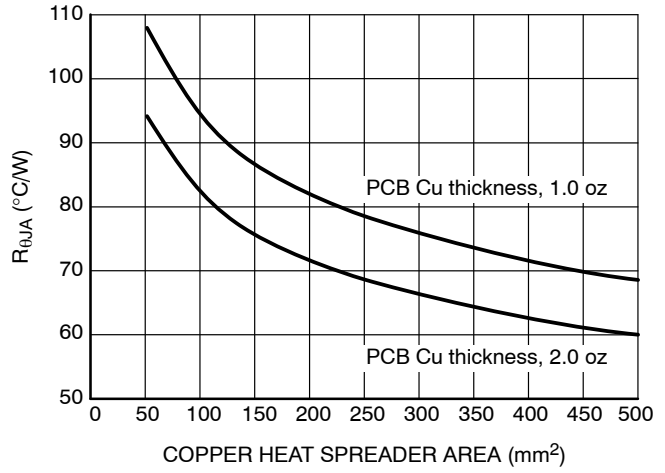


Figure 16. $R_{\theta JA}$ vs. Copper Area

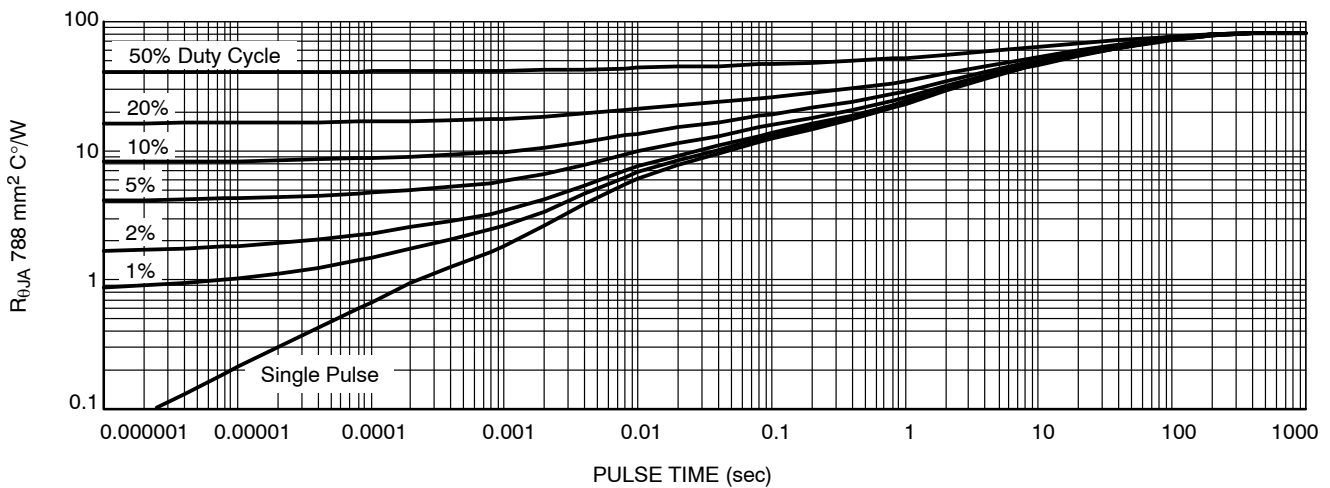
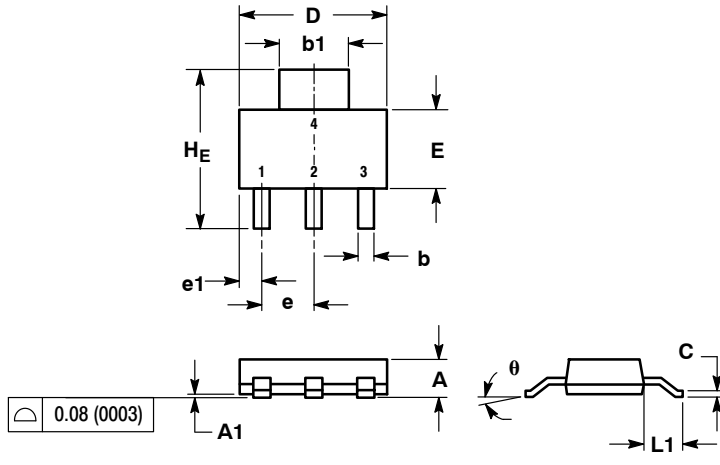


Figure 17. Transient Thermal Resistance

NCV8440

PACKAGE DIMENSIONS

SOT-223 (TO-261)
CASE 318E-04
ISSUE L

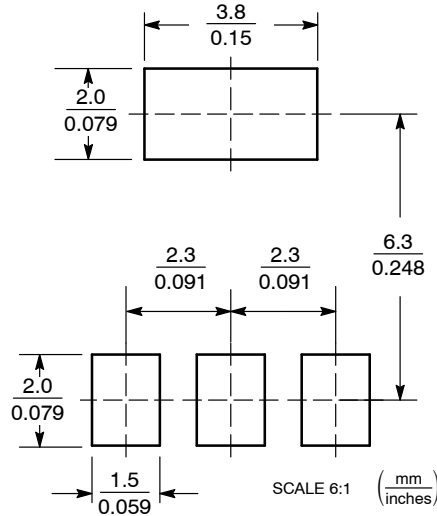


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

| DIM | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|--------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 1.50 | 1.63 | 1.75 | 0.060 | 0.064 | 0.068 |
| A1 | 0.02 | 0.06 | 0.10 | 0.001 | 0.002 | 0.004 |
| b | 0.60 | 0.75 | 0.89 | 0.024 | 0.030 | 0.035 |
| b1 | 2.90 | 3.06 | 3.20 | 0.115 | 0.121 | 0.126 |
| c | 0.24 | 0.29 | 0.35 | 0.009 | 0.012 | 0.014 |
| D | 6.30 | 6.50 | 6.70 | 0.249 | 0.256 | 0.263 |
| E | 3.30 | 3.50 | 3.70 | 0.130 | 0.138 | 0.145 |
| e | 2.20 | 2.30 | 2.40 | 0.087 | 0.091 | 0.094 |
| e1 | 0.85 | 0.94 | 1.05 | 0.033 | 0.037 | 0.041 |
| L1 | 1.50 | 1.75 | 2.00 | 0.060 | 0.069 | 0.078 |
| HE | 6.70 | 7.00 | 7.30 | 0.264 | 0.276 | 0.287 |
| θ | 0° | - | 10° | 0° | - | 10° |

- STYLE 3:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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